

This Page Is Inserted by IFW Operations
and is not a part of the Official Record

BEST AVAILABLE IMAGES

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images may include (but are not limited to):

- BLACK BORDERS
- TEXT CUT OFF AT TOP, BOTTOM OR SIDES
- FADED TEXT
- ILLEGIBLE TEXT
- SKEWED/SLANTED IMAGES
- COLORED PHOTOS
- BLACK OR VERY BLACK AND WHITE DARK PHOTOS
- GRAY SCALE DOCUMENTS

IMAGES ARE BEST AVAILABLE COPY.

**As rescanning documents *will not* correct images,
please do not report the images to the
Image Problem Mailbox.**

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 08-083877
(43)Date of publication of application : 26.03.1996

51)Int.Cl.

H01L 23/50
H01L 23/28

21)Application number : 07-022243

(71)Applicant : SONY CORP

22)Date of filing : 17.01.1995

(72)Inventor : NAKANO SEIJI
MOGAMI KEIICHI

30)Priority

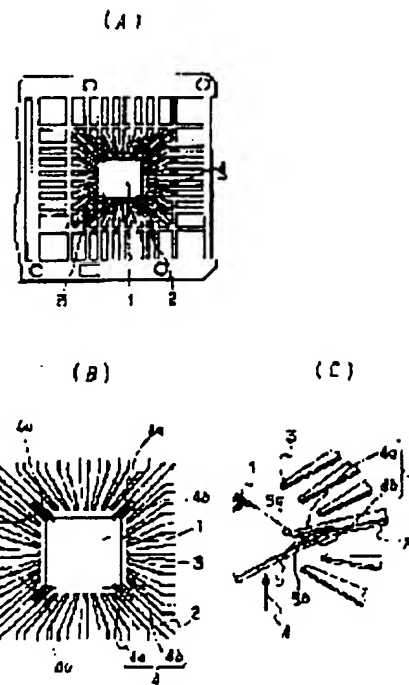
Priority number : 06182917 Priority date : 12.07.1994 Priority country : JP

54) LEAD FRAME

57)Abstract:

PURPOSE: To prevent deformation or open circuit of a wire, package track, and the like due to variation in the position or direction, especially floating, of a die pad or a semiconductor element supported hereon caused by the pressure of resin at the time of resin sealing by enhancing the mechanical strength at the depress part of a support lead.

CONSTITUTION: In a lead frame where the root part of a lead 2 supporting a die pad 1 which supports a semiconductor element is depressed, the depressed part 4 of the support lead 2 is split into a plurality of subsections 4a, 4b. One subsection 4a is set longer than the other subsection 4b wherein the subsections 4a, 4b and the support lead 2 of the die pad 1 substantially define a triangle, when the depressed part is viewed from the side, thus providing a reinforcing part.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the

examiner's decision of rejection or application
converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of
rejection]

[Date of requesting appeal against examiner's
decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office